

PAD AREA
 KEEP OUT AREA

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

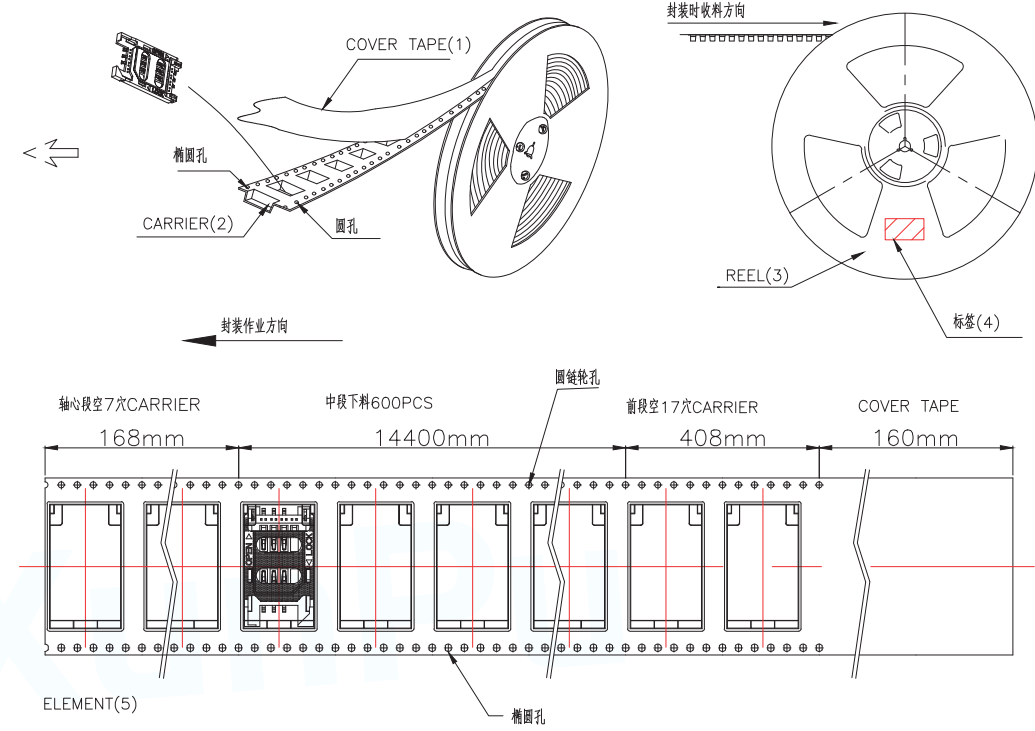
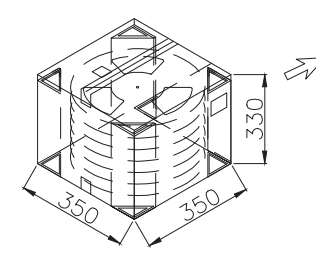
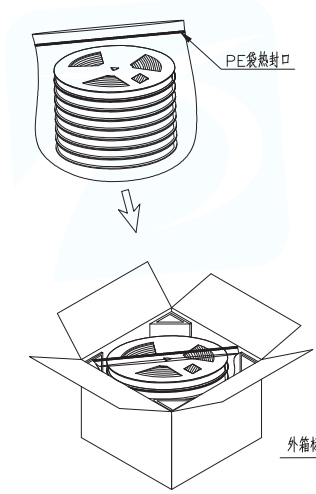
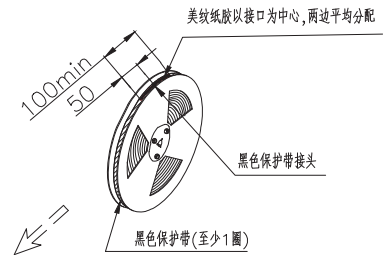
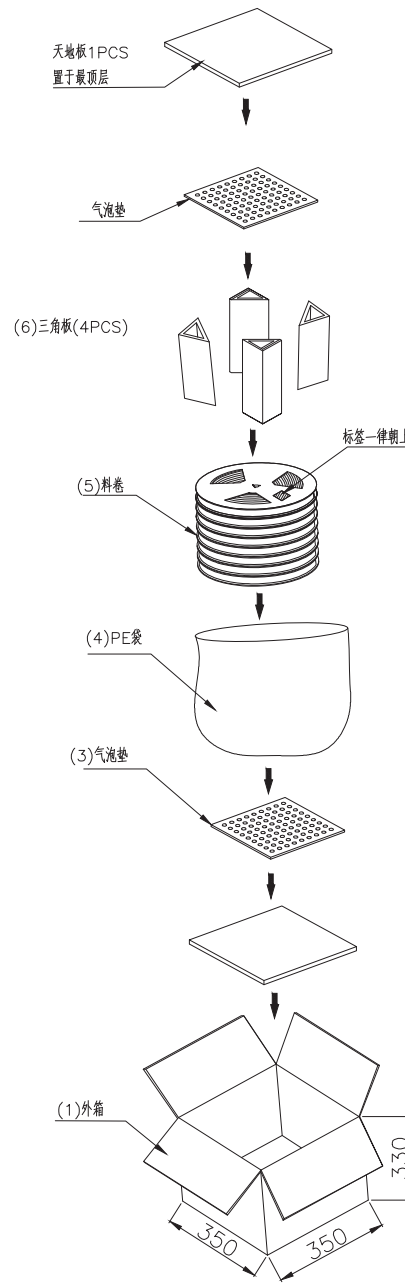
MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

Q8 SPECIFICATION:

- 1.寿命:10000CYCLES MIN.
- 2.CONTACT FORCE:0.2~1.0N.(卡片厚度0.76MM)
- 3.接触阻抗:50MΩ, TYPICAL,100MΩ MAX.
- 4.绝缘阻抗:MIN 1000MΩ/500V DC .
- 5.OPEN/LOCK FORCE: 6N ± 3N
- 6.平贴:IR前后CP8 0.10MM MAX;塑胶0.20MM MAX.
- 7.QX为重点检验尺寸.

Table A

材质	塑胶	LCP E130i BK HF
	端子	C5210R-H T=0.20mm HF
端子电镀	整体打镍底50U”MIN,接触区刷金3U”MIN,焊接区浸镀纯零锡100U”MIN.	
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE:MINI SIM CARD HINGED 全塑 6P无柱
DECIMALS:		PAR
ANGLES:		SIM-107-ARP6
X.X:±0.15	X.':±3°	DWN
X.XX:±0.10	X.X':±2°	CHKD
X.XXX:±0.08	X.XX':±1°	APVD
CUSTOMER COPY		SCALE1:1 UNIT:MM
		SIZE:A4 SHEET:1F1
		REV:A



一、包装流程:

1. 成品置于Carrier Tape中, 金属零件以不接触Carrier Tape为原则.
2. 以冷封式Cover Tape与REEL紧密封好, 每盘REEL共装600Pcs成品;
3. 每盘包装好后需在REEL带外圈用黑色保护带绕1圈包好, 并以至少100mm的美纹纸封口;
4. 将成品之Label贴于REEL椭圆定位孔另一边之卷盘上;
5. 先置入一瓦楞纸板于纸箱底部, 再置一张气泡布于瓦楞纸上, 后将Reel平置于一防水袋, 标签统一朝上装放(一箱共装6个Reel), 封好口后置于箱中;
6. 将三角板置于箱中四个角落, 再置入一张气泡布于Reel之上, 后置一块瓦楞纸于最顶层;
7. 以Tape封合, 并贴上成品包装标签.

二、包装要求:

1. 成品包装前后均需空穴, 具体要求如图所示;
2. 三角板置入箱中须高于REEL重叠总高度, 但需低于纸箱顶部15mm以上, 以確保封口后不会有外溢现象;
3. REEL叠不可有晃动现象.

三、尾数箱包装流程及要求同上.

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MINI SIM CARD HINGED 全塑 6P无柱 包装图	
DECIMALS:	ANGLES:		PAR	SIM-107-ARP6
X.X:±0.15	X.':±3°		DWN	
X.XX:±0.10	X.X':±2°		CHKD	
X.XXX:±0.08	X.XX':±1°	APVD		
CUSTOMER COPY		SCALE:1:1	UNIT:MM	REV:A
		SIZE:A4	SHEET:1F1	